

### FEATURES

- \* Ideal for printed circuit board
- \* Reliable low cost construction utilizing molded plastic technique
- \* High surge current capability
- \* Polarity: Symbol molded on body
- \* Mounting position: Any
- \* Weight: 0.14 grams

#### Case Style

DIM	DIMENSIONS				NOTE
	INC HES		MM		
	MIN	MAX	MIN	MAX	
A	.195	.205	4.95	5.21	
B	.095	.105	2.41	2.67	
C	.144	.161	3.65	4.10	
D	.179	.190	4.55	4.83	
E	.039	.049	0.99	1.24	
F	.090	.106	2.30	2.70	
G	.017	.029	0.43	0.74	
H	.132	.148	3.35	3.75	
K	.006	.016	0.15	0.41	
L	.137	.147	3.48	3.73	
M	10°	15°	10°	15°	
N	.020	.028	0.51	0.71	

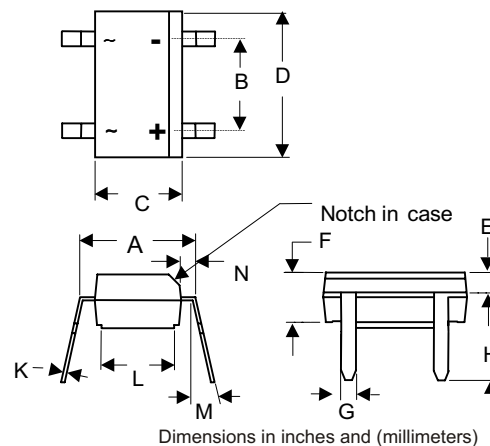
### VOLTAGE RANGE

50 to 1000 Volts

### CURRENT

0.8 Ampere

MB-1



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

TYPE NUMBER	MB05M	MB1M	MB2M	MB4M	MB6M	MB8M	MB10M	UNIT
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at Ta=40°C (Note 1)	0.8							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	3.0							A
Maximum Forward Voltage Drop per Bridge Element at 0.4A D.C.	1.0							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	5.0							µA
Typical Thermal Resistance R <sub>JA</sub> (Note 2)	75							°C/W
Operating Temperature Range, T <sub>J</sub>	-55 — +150							°C
Storage Temperature Range, T <sub>STG</sub>	-55 — +150							°C

NOTES: 1. Mounted on P.C. Board.  
2. Thermal Resistance Junction to Ambient.

## RATING AND CHARACTERISTIC CURVES (MB05M THRU MB10M)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

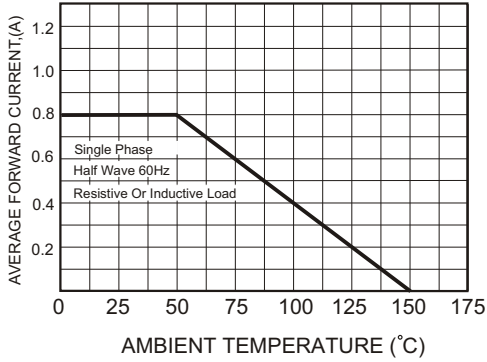


FIG.2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

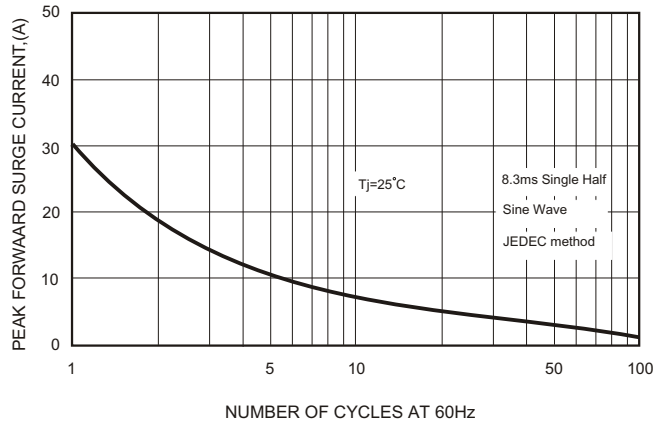


FIG.3-TYPICAL FORWARD CHARACTERISTICS

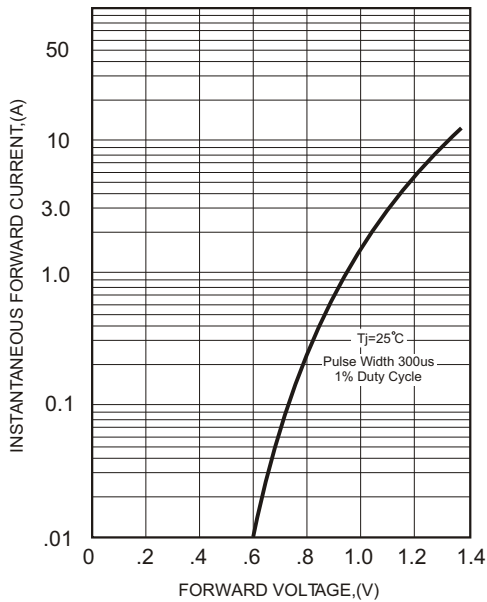


FIG.4-TYPICAL REVERSE CHARACTERISTICS

